

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An integrated optical emitter device, comprising:
a substrate;
an emitter mounted to said substrate;
a molded cup that surrounds said emitter and that is bonded to said substrate; and
a molded encapsulation layer that encapsulates said emitter and that is bonded to said molded cup, wherein said molded encapsulation layer is shaped to direct light emitted by said emitter such that the molded encapsulation layer reduces a difference in beam divergence between a fast-axis and a slow-axis of said emitter.
2. (Original) The integrated optical emitter device of claim 1, wherein said substrate is a printed circuit board.
3. (Original) The integrated optical emitter device of claim 1, wherein said emitter is selected from the list consisting of: an edge emitting diode and a surface emitting diode.
4. (Original) The integrated optical emitter device of claim 1 wherein said molded cup and molded encapsulation layer are formed of molded epoxy.
5. (Original) The integrated optical emitter device of claim 1 wherein said molded cup is at least semi-reflective.
6. (Canceled)
7. (Currently Amended) The integrated optical emitter device of claim [[6]] 1 wherein said molded encapsulation layer is elliptical.
8. (Canceled)
9. (Original) The integrated optical emitter device of claim 1 wherein said encapsulation layer is formed from clear epoxy.

10. (Original) The integrated optical emitter device of claim 1 wherein said molded cup possesses a plurality of discrete transitions.

11-18. (Cancelled)

19. (Currently Amended) An integrated optical emitter device, comprising:
a printed circuit board (PCB);
an emitter mounted to said PCB;
a molded epoxy cup that surrounds said emitter and that is bonded to said PCB,
wherein said molded epoxy cup is at least semi-reflective; and
a molded epoxy encapsulation layer that encapsulates said emitter and that is bonded to said molded epoxy cup, wherein said molded encapsulation layer is shaped to direct light emitted by said emitter such that the molded encapsulation layer reduces a difference in beam divergence between a fast-axis and a slow-axis of said emitter.

20. (Currently Amended) The integrated optical emitter device of claim 19,
wherein said molded encapsulation layer ~~possesses an~~ is elliptical shape ~~and wherein said elliptical shape is aligned to reduce a difference in axis beam divergence from said emitter.~~